

# A pixel TPC for the Linear Collider: Towards a demonstrator module

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GEFÖRDERT VOM



Bundesministerium  
für Bildung  
und Forschung



LCTPC Collaboration Meeting  
DESY 30.06.2014



# Outline



- LCTPC-pixel collaboration
- Timepix Chip
- 2013 Testbeam and data analysis
- New demonstrator module
- Summary

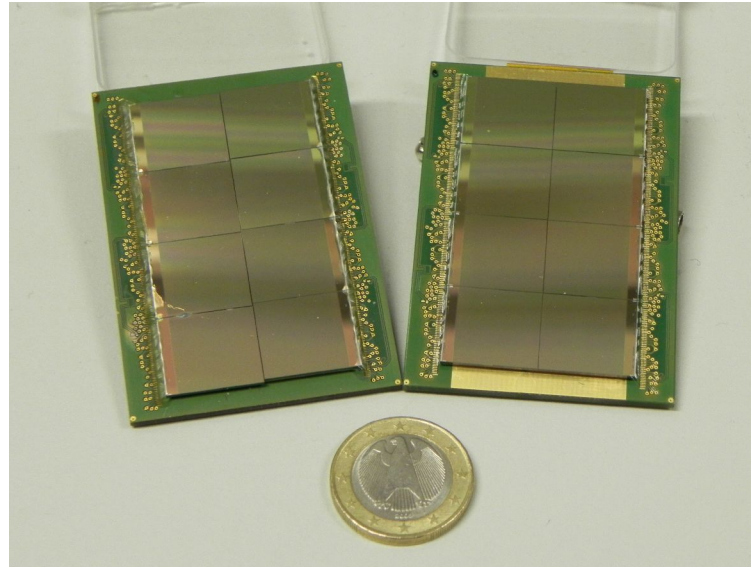
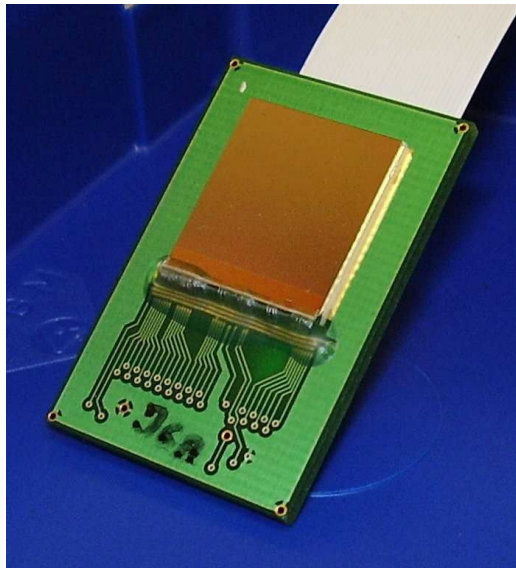


- R&D towards a pixel-TPC: MPGD + pixel readout
- Groups:
  - NIKHEF: Module construction
  - University of Kiew: Simulation
  - LAL Orsay: Simulation
  - CEA Saclay / DESY: Data analysis
  - Uni Bonn: Module construction, readout system, data analysis
  - Uni Siegen: Data analysis
- Goal: build a demonstrator module for a pixel-TPC

# Timepix chip



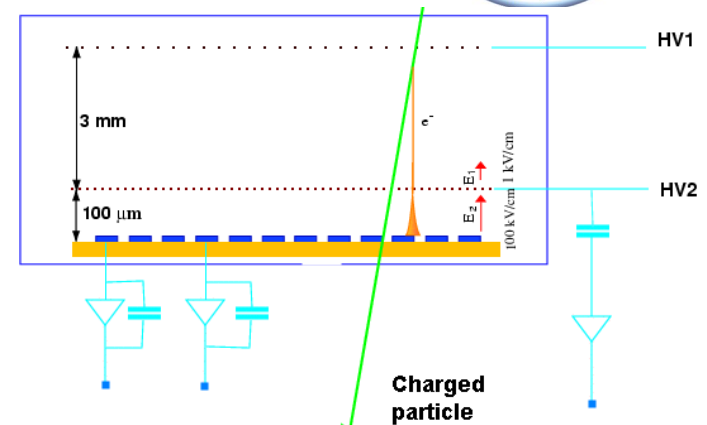
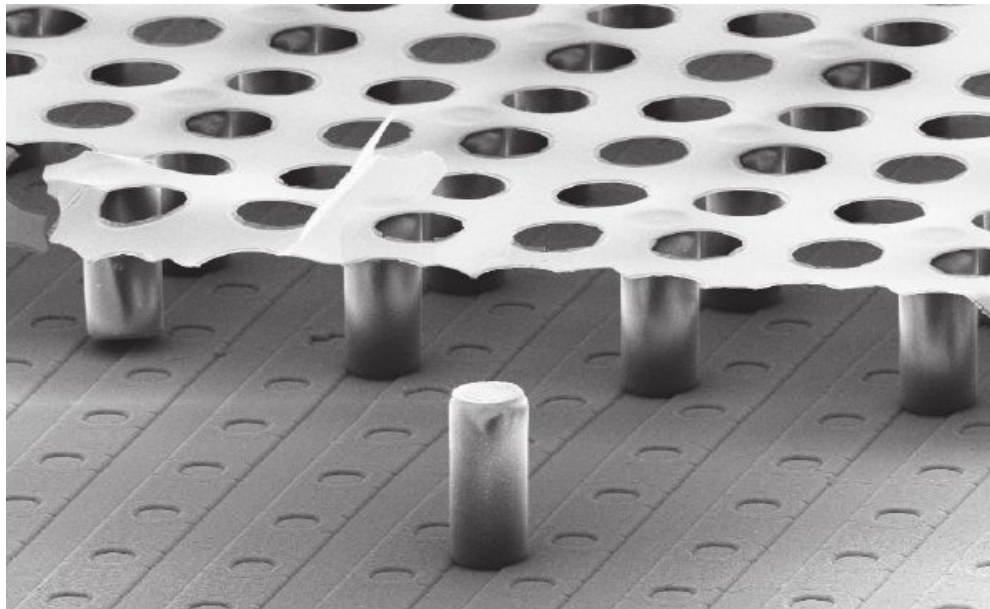
- Universal readout chip
- Properties:
  - active surface:  $1.4 \times 1.4 \text{ cm}^2$
  - pixel size  $55 \times 55 \mu\text{m}^2$
  - $256 \times 256$  pixel array
  - 14 bit counter in each pixel (ToA or ToT)
  - Noise threshold  $\sim 500e^-$  (ENC  $\approx 90e^-$ )



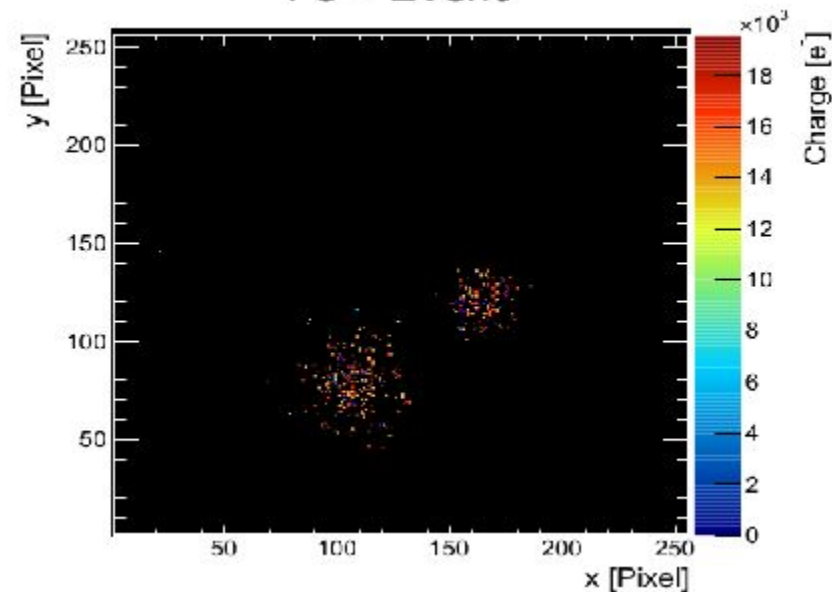
# Timepix+Micromegas=InGrid



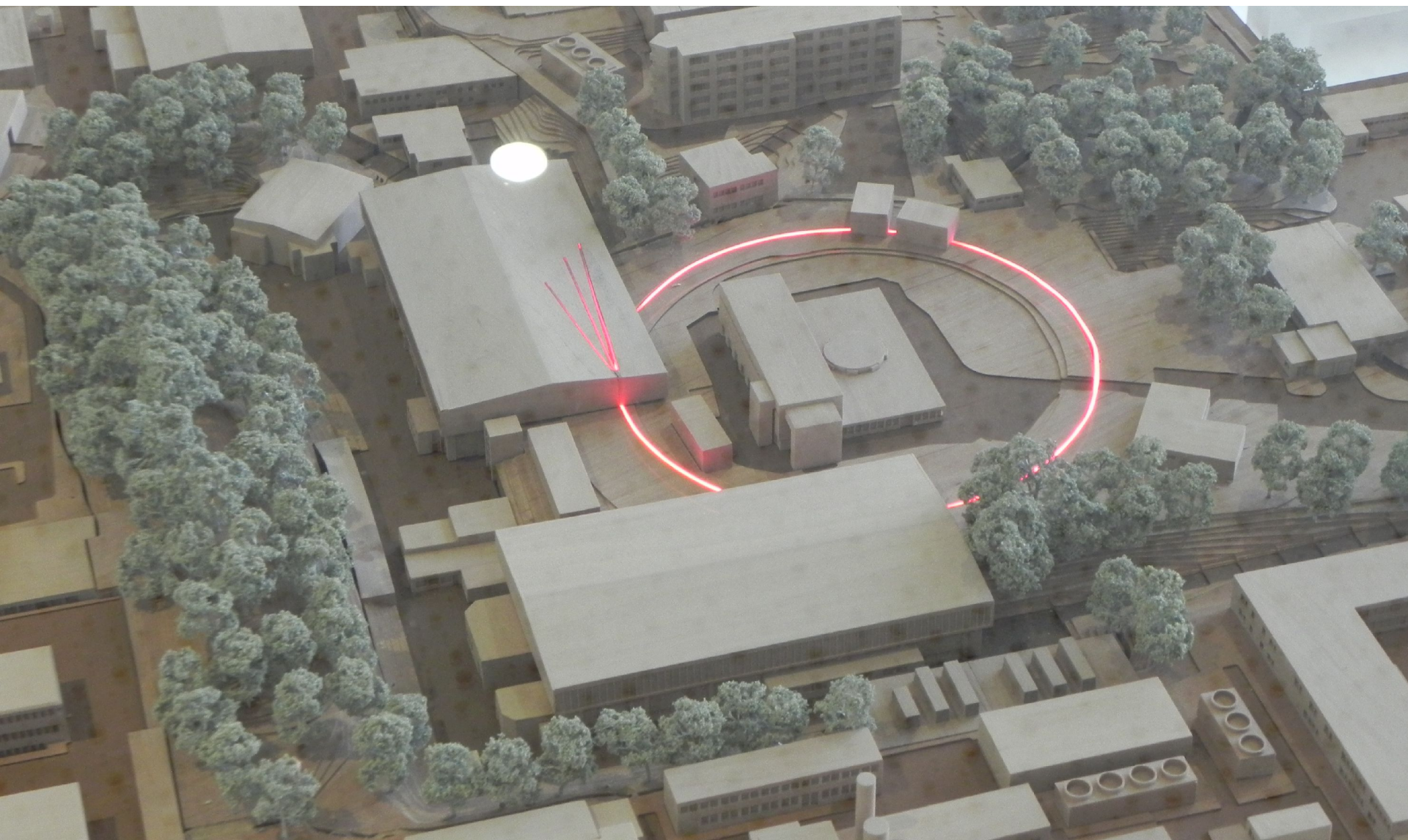
- Aluminium mesh on chip
- Use photolithographic process
  - Hole to pixel alignment
  - Pillar height uniformity



$^{55}\text{Fe}$  - Event

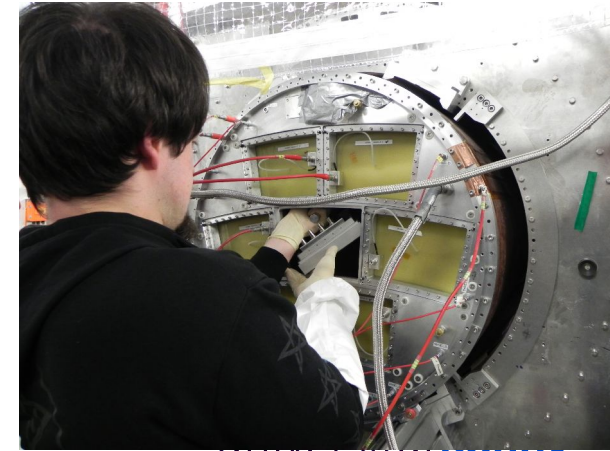
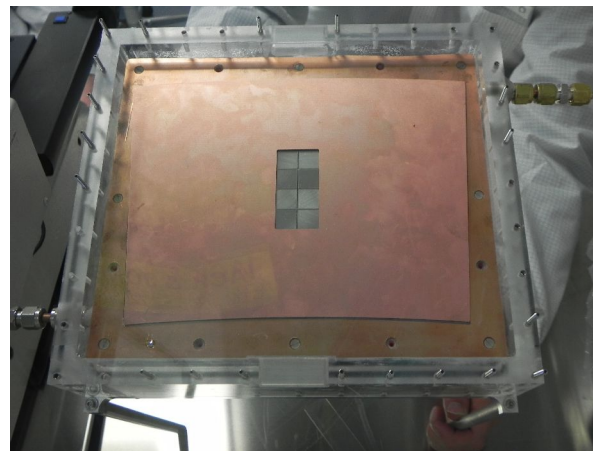
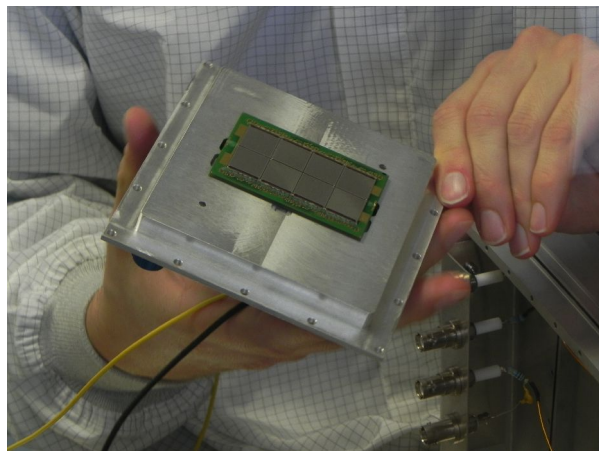
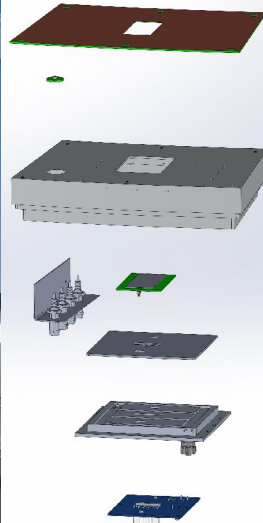
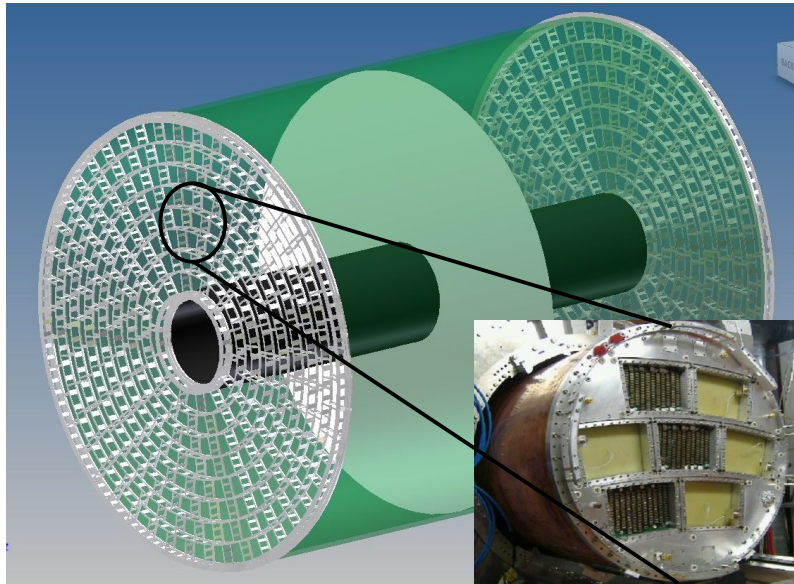


# 2013 test beam

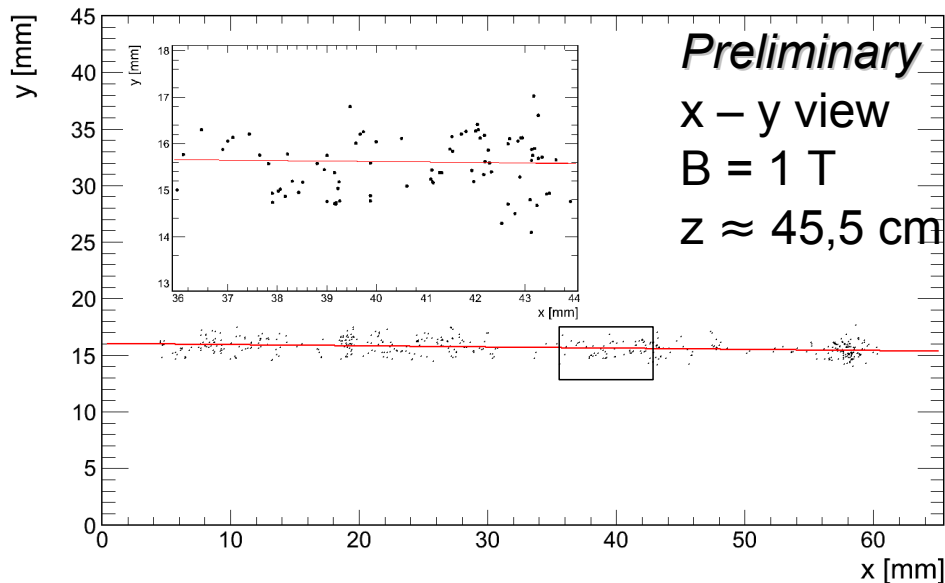
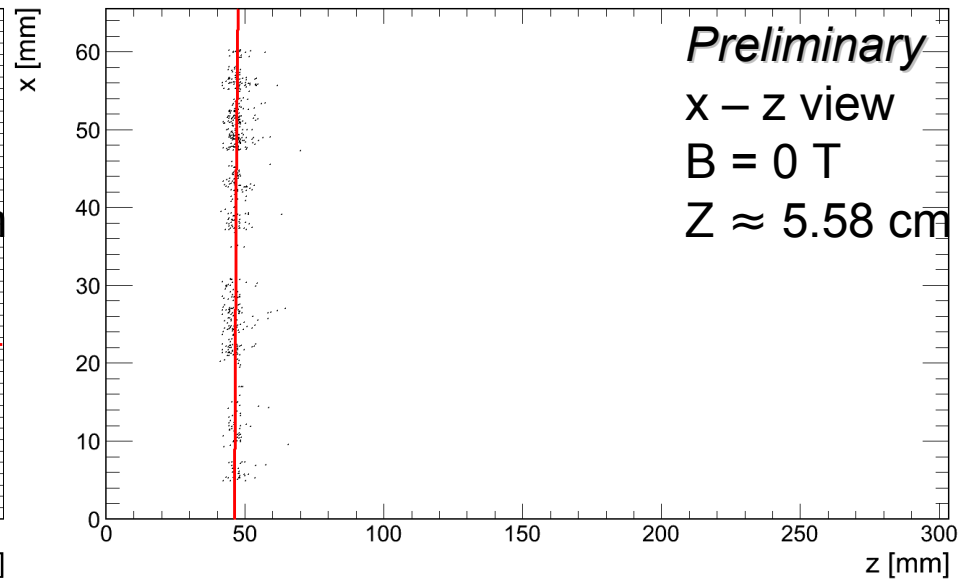
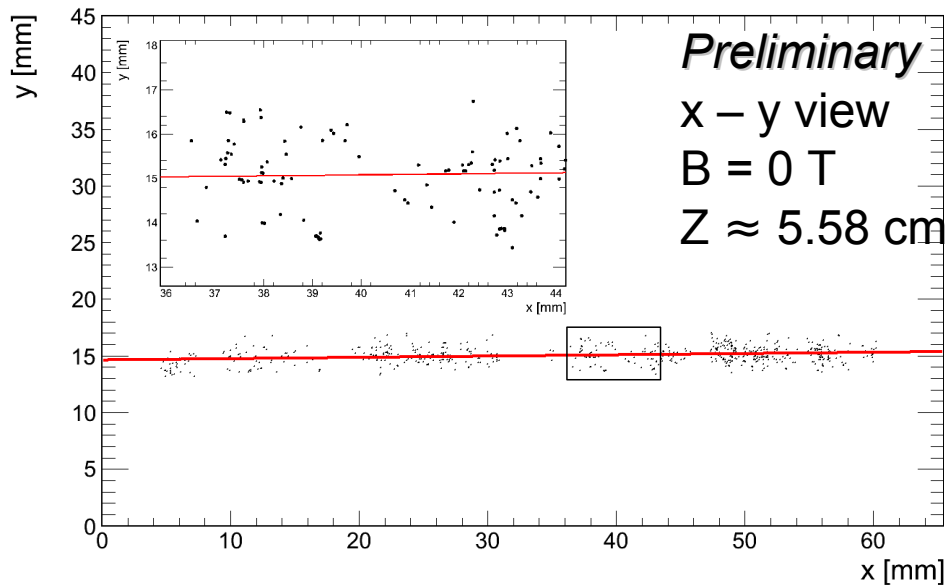


# 2013 test beam

Setup at DESY



# Reconstructed tracks





# LP module: next steps



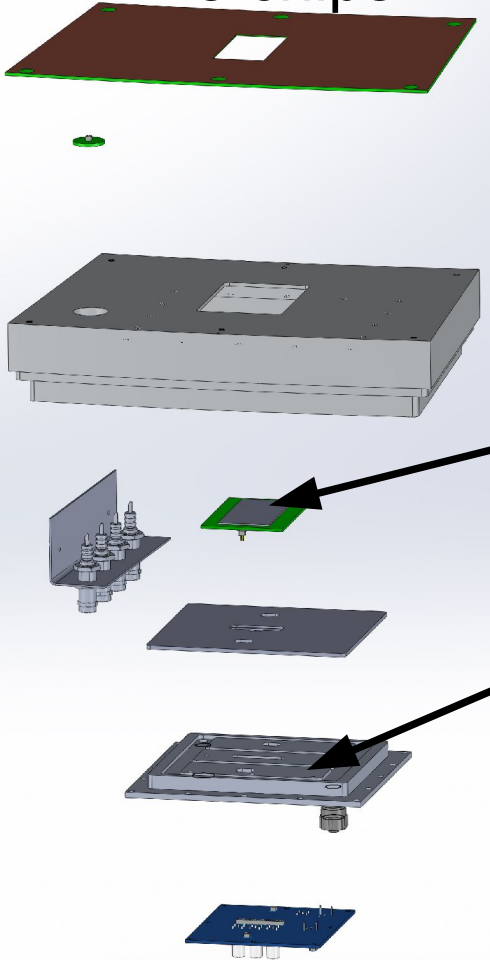
~100 chip module (cover 50% of area, 6 mio. channels)

- Project: test a 32 InGrid board in September/October
  - Similar design as 8 InGrid module
  - Expandable to 96 InGrids
- Mechanical design (Bachelor student: Johann Tomtschak)
  - CAD drawings in SolidWorks
  - Construction of light LP frame in workshop
  - Construction of chip support structure in workshop
  - Use water cooling

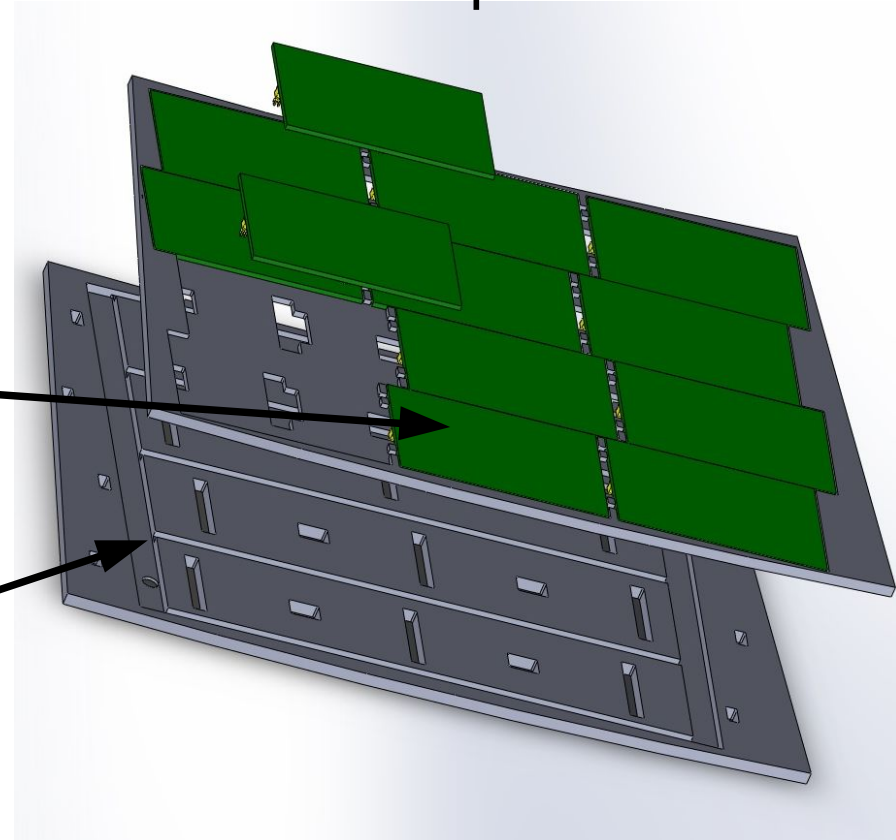
# InGrid modules



2013  
8 chips



2014  
96 chips



# LP module: next steps

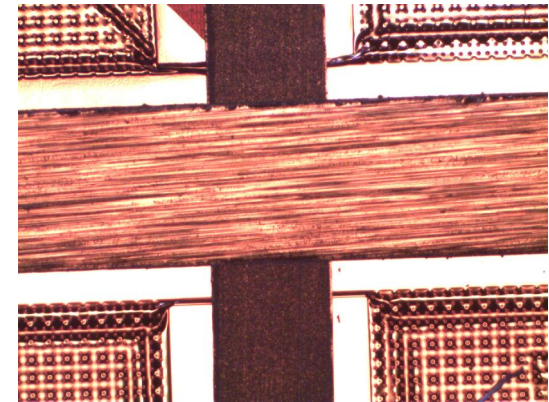
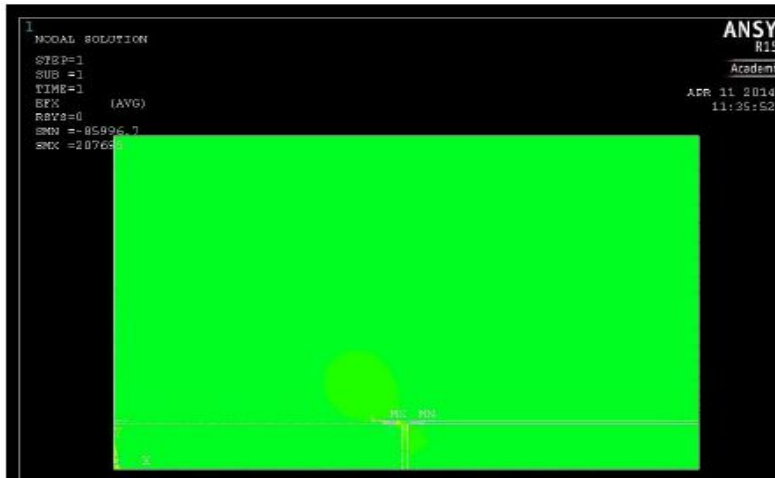
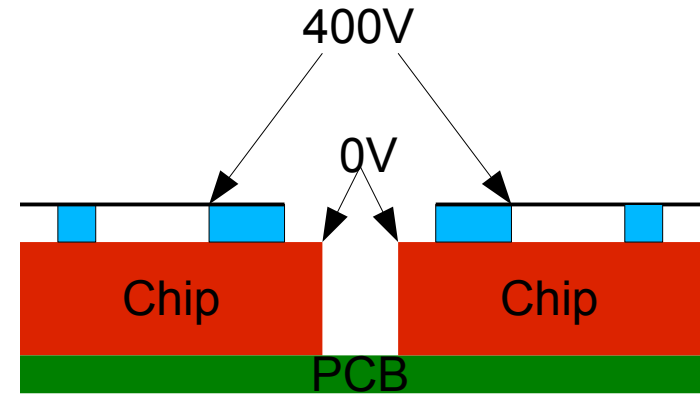
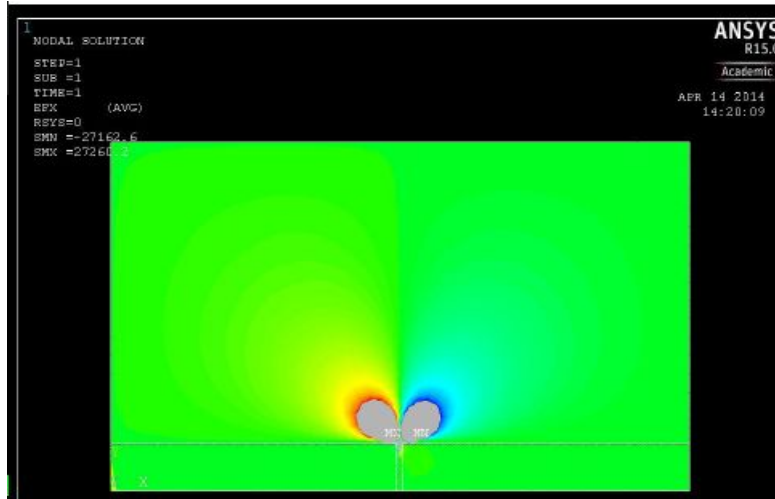


~100 chip module

- Powering (Bachelor student: Katrin Kohl)
  - Was already critical for a single octoboard
  - Low voltage supply for 4/12 octoboards?
  - High voltage supply
- Field distortions between chips (Katrin Kohl)
  - Simulation, implementation and measurements with „road-like strips“
- PCB layout (Jochen Kaminski)
  - Depends on powering
  - Space is limited
  - Need many HDMI cables
- InGrid bonding, testing, quality control, calibration

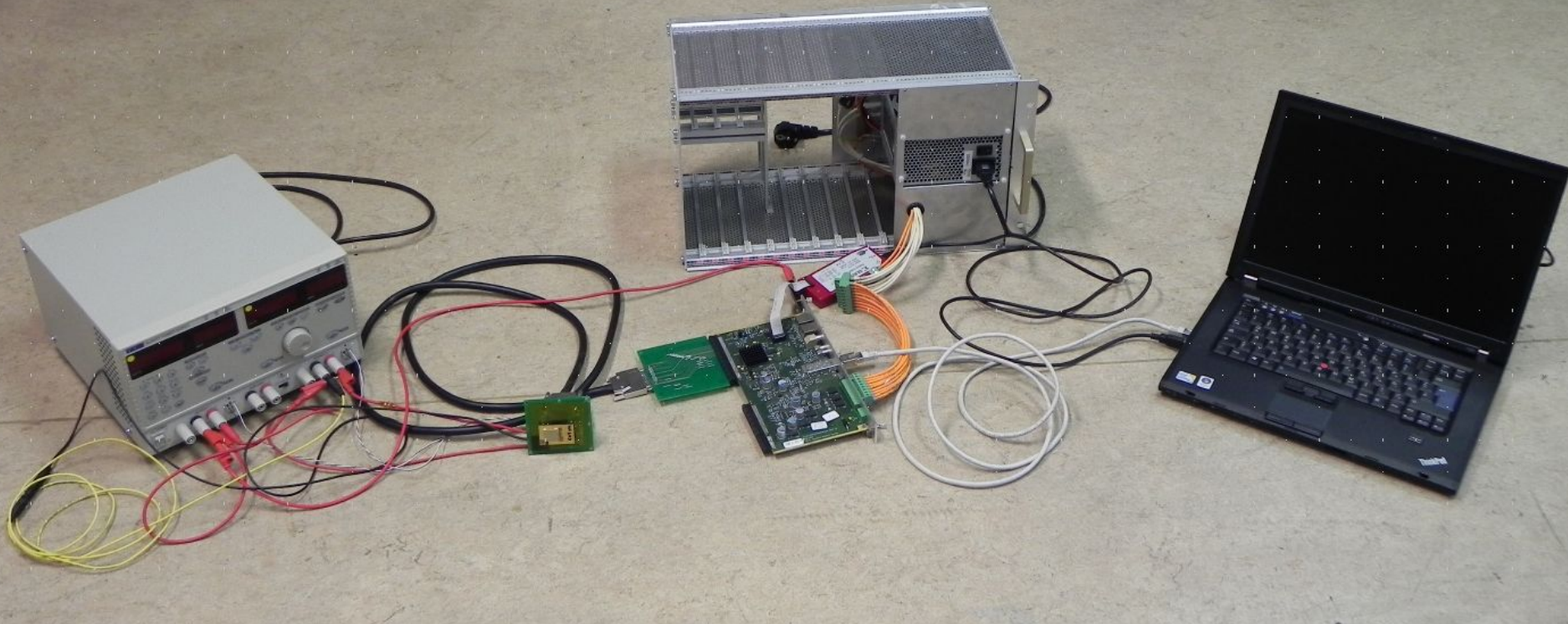


# Field distortions

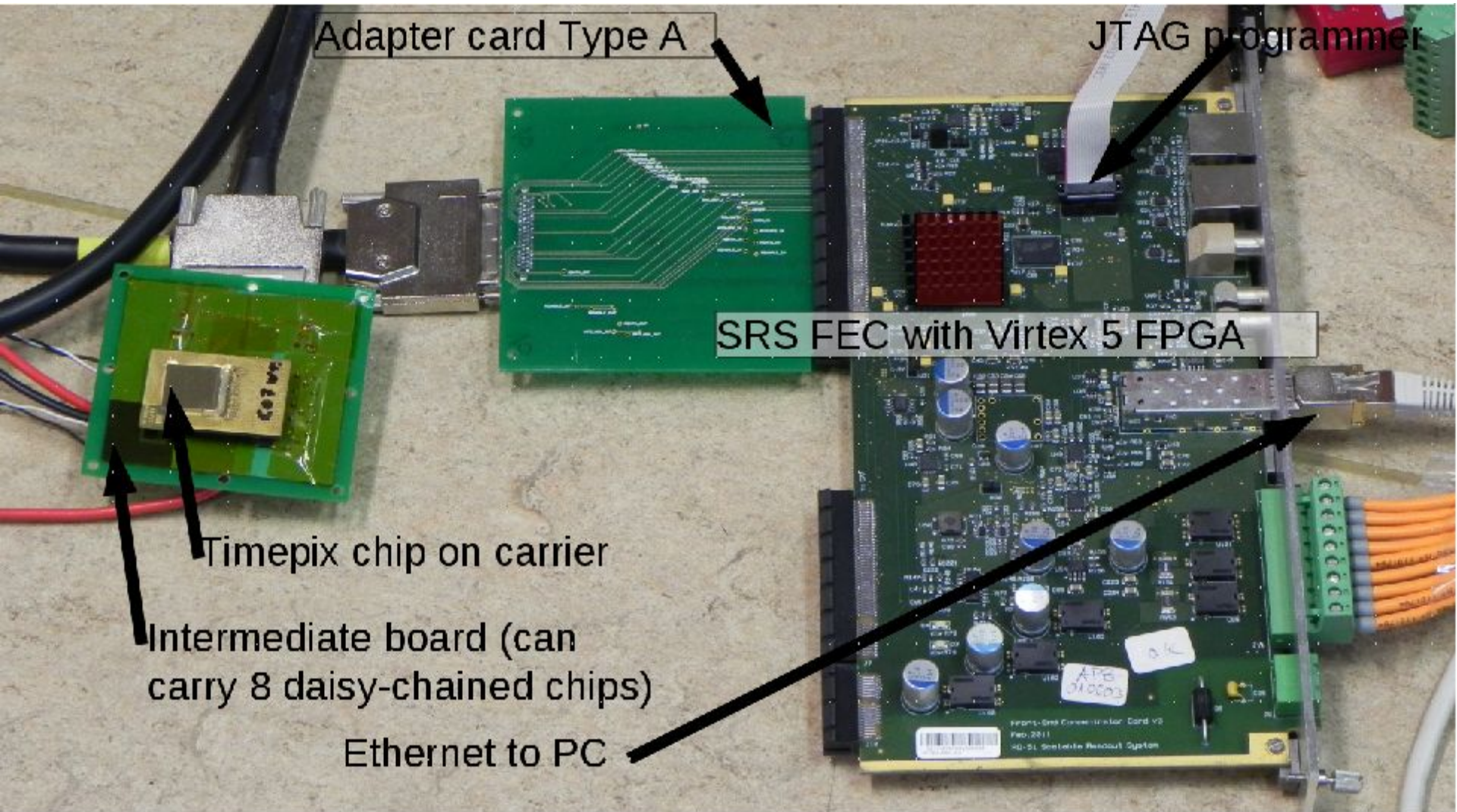


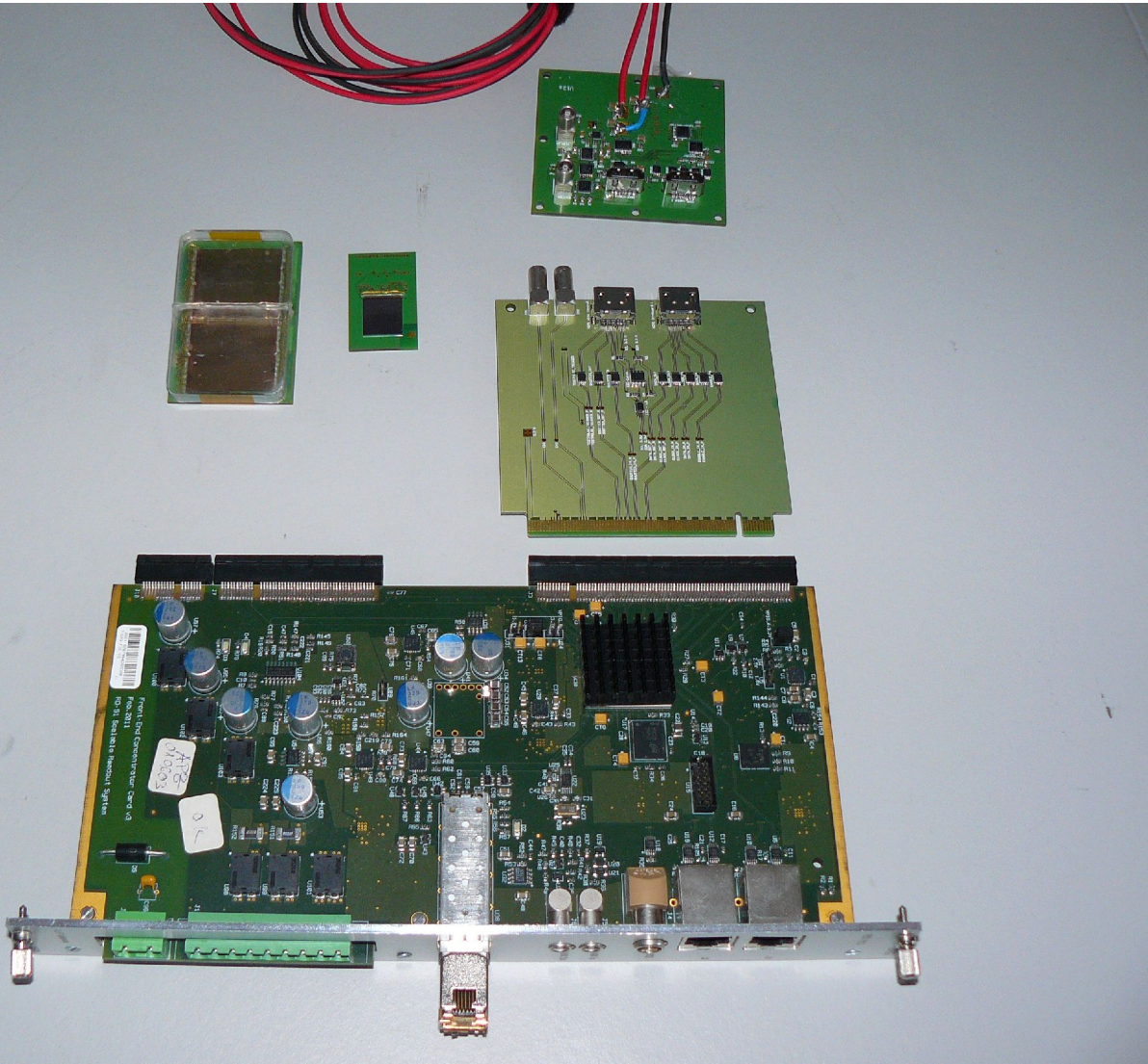
# Readout system

Scalable Readout System (RD51, CERN)



Chain: Chip – Adapter card+FEC – Computer





# Readout system status



- FEC5 based readout worked very well at testbeam
  - Virtex5 FPGA, DDR2 RAM
  - Readout of one octoboard
  - Updates of firmware
  - New hardware e.g. HDMI cables, intermediate boards
- For 96 chip module:
  - 4 octoboards / FEC
  - 3 FECs
- FEC6
  - Virtex6 FPGA, large internal memory
  - 3 FEC6 arrived in Bonn in April
  - Code migration started
  - Design of LP module shaped intermediate board for 12 octoboards started

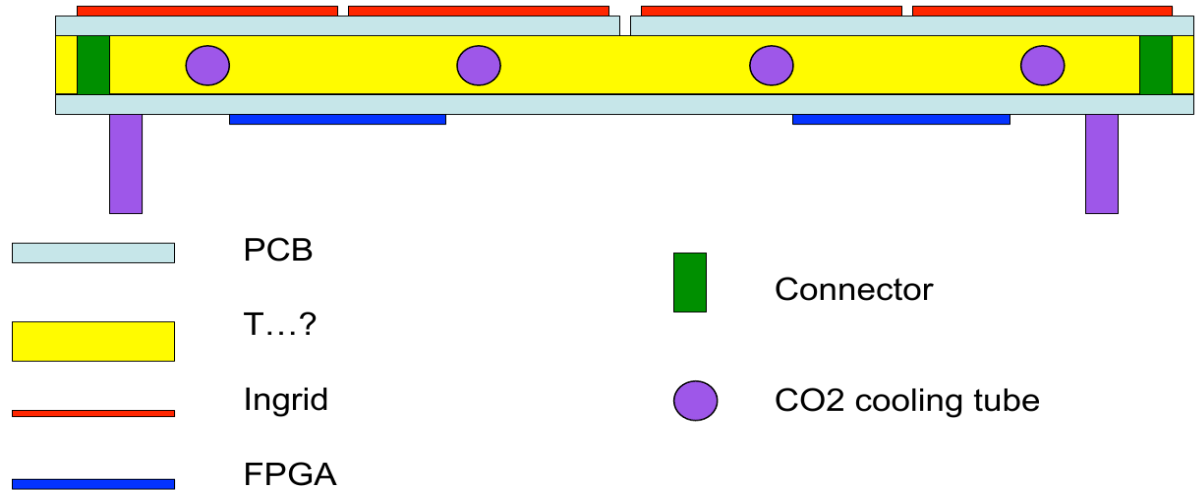


# Outlook

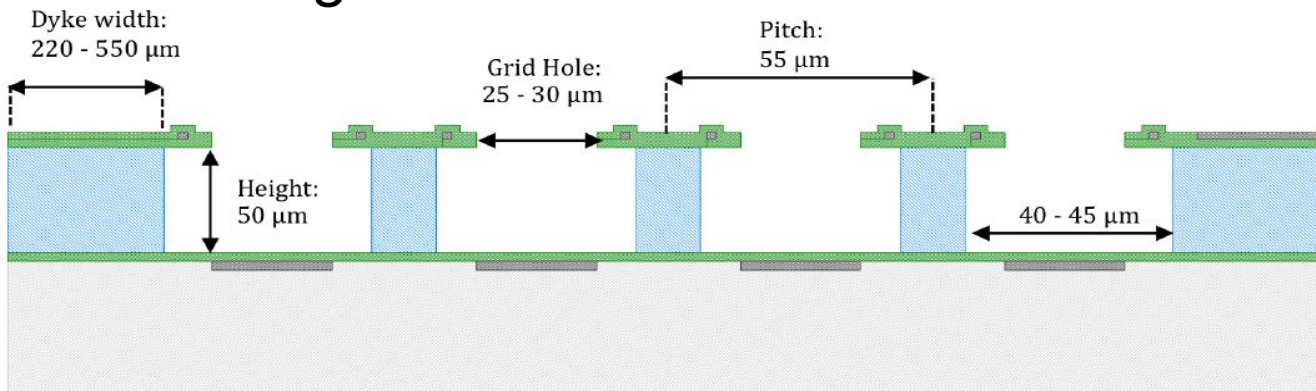


- Fully integrated module (Jan Timmermans)

- Timepix3

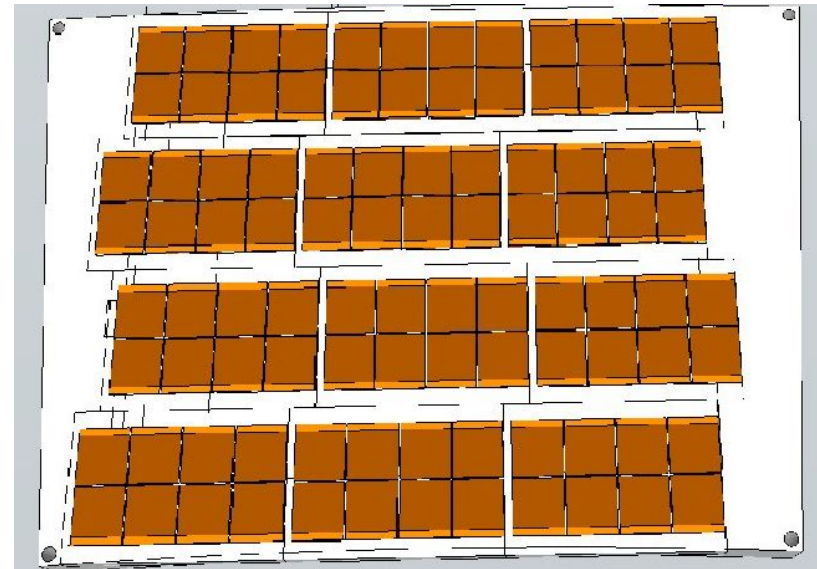


- All ceramic grid



Pixel-TPC project advances very well

- Successful testbeam 2013
- Data analysis ongoing
- Development of readout system
- Design of a 32 / 96 chip module



=> Demonstrator for a pixel-TPC at the end of this year

Timepix 3, Ceramic grid

# Collaborators



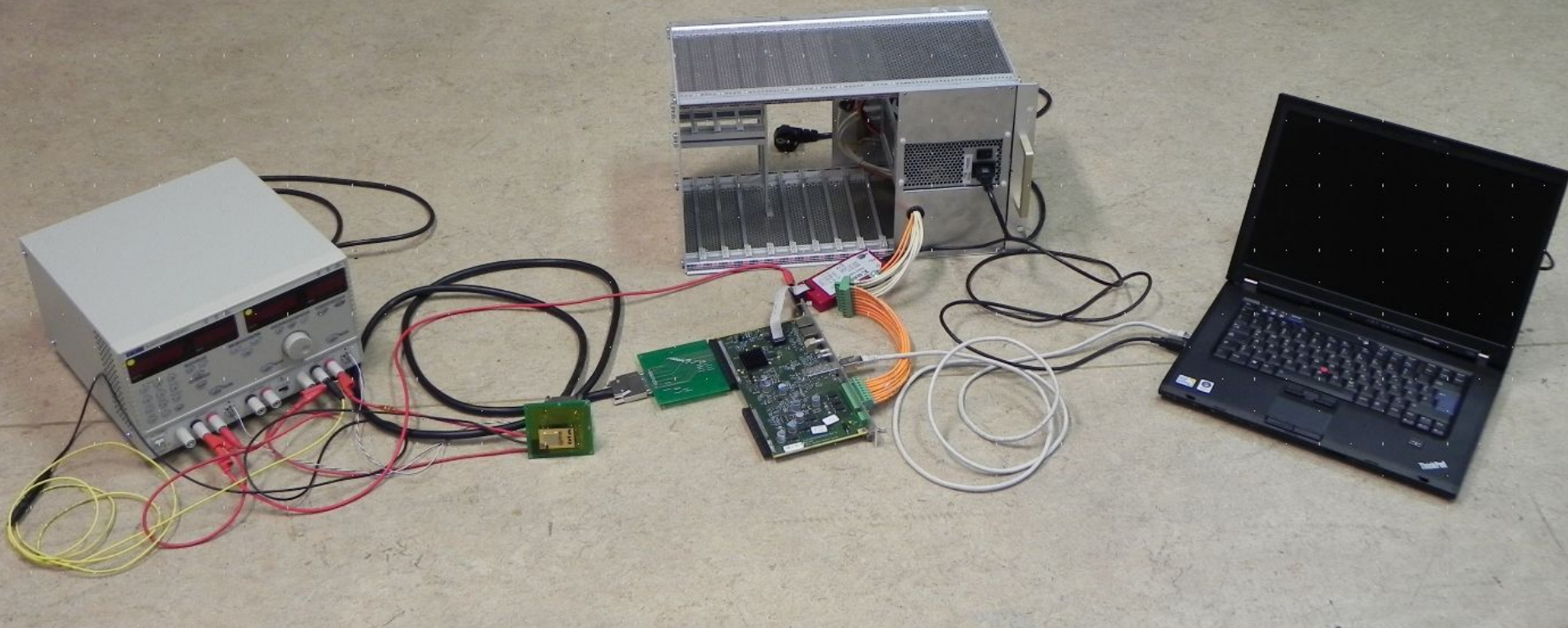
## LCTPC-pixel:

- CEA Saclay: Andrii Chaus, David Attié, Maxim Titov, Paul Colas
- DESY: Felix Müller, Ralf Diener, Ties Behnke
- NIKHEF: Fred Hartjes, Harry van der Graaf, Jan Timmermans, Rolf Schön, Wilko Koppert
- Uni Bonn: Alexander Deisting, Christoph Krieger, Jochen Kaminski, Johann Tomtschak, Kathrin Kohl, Klaus Desch, Michael Lupberger, Robert Menzen, Thorsten Krautscheid, Yevgen Bilevich,
- LAL Orsay/Uni Kiew: Sergey Barsuk, Oleg Bezshyyko, Oleksiy Fedorchuk
- Uni Siegen: Amir Shirazi, Ivor Fleck

Special thanks to: Fraunhofer IZM, LCTPC Collaboration, DESY testbeam support

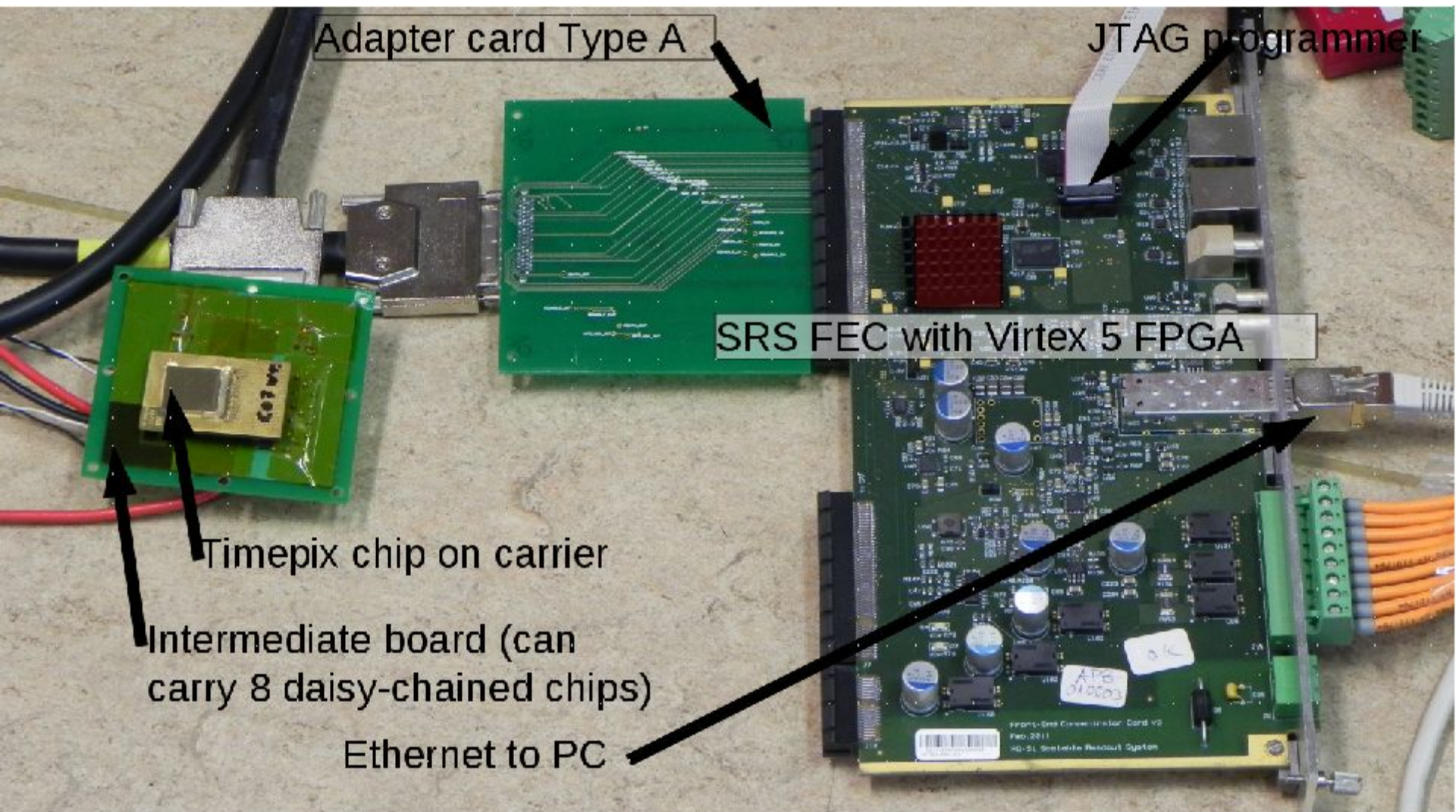
# Readout system

Scalable Readout System (RD51, CERN)



Chain: Chip – Adapter card+FEC – Computer

# SRS with Timepix chip





# 2013 test beam



March/April 2013: 2 LCTPC octoboard modules

- Different amplification structures: GEM / InGrid
- Test of readout system
- Readout rate: 2.5 Hz; 40MHz clock
- Electron beam of up to 6 GeV
- Gas: Ar:CF<sub>4</sub>:iC<sub>4</sub>H<sub>10</sub> (95:3:2) = T2K gas
- ~ 2 Mio. frames recorded, including B = 1 T
- Extensive testbeam program
- Preliminary data analysis in MarlinTPC Robert Menzen

# Preliminary Analysis: Cuts



Dataset for first analysis:

z-scan,  $B=0$  T,  $E_{\text{Drift}} = 230$  V/cm ( $D_T = 311$   $\mu\text{m}/\sqrt{\text{cm}}$ )

$\Rightarrow$  tracks parallel to x-axis

Cuts:

- Only hits within shutter window
- More than 200 hits per track



# Preliminary Analysis: Cuts



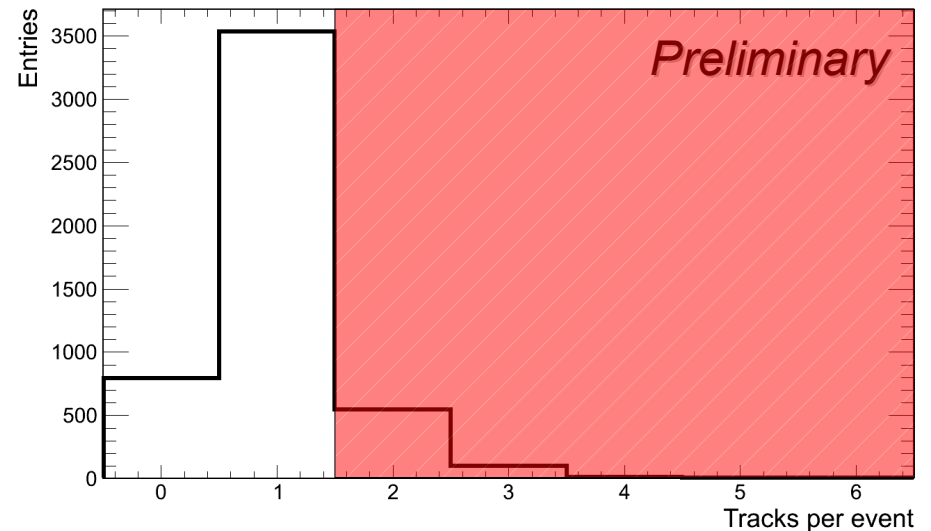
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Cuts:

- Only hits within shutter window
- More than 200 hits per track
- Only single track events



# Preliminary Analysis: Cuts



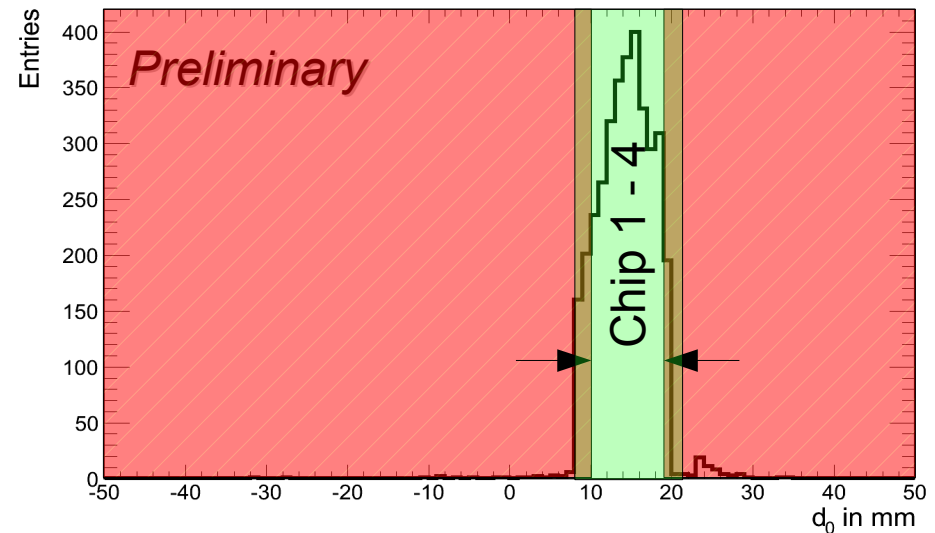
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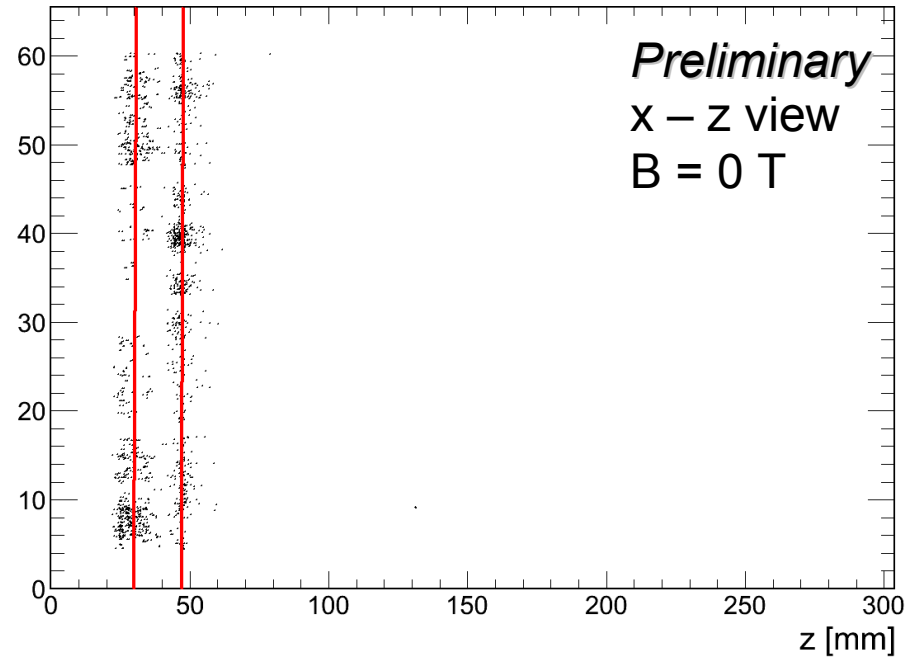
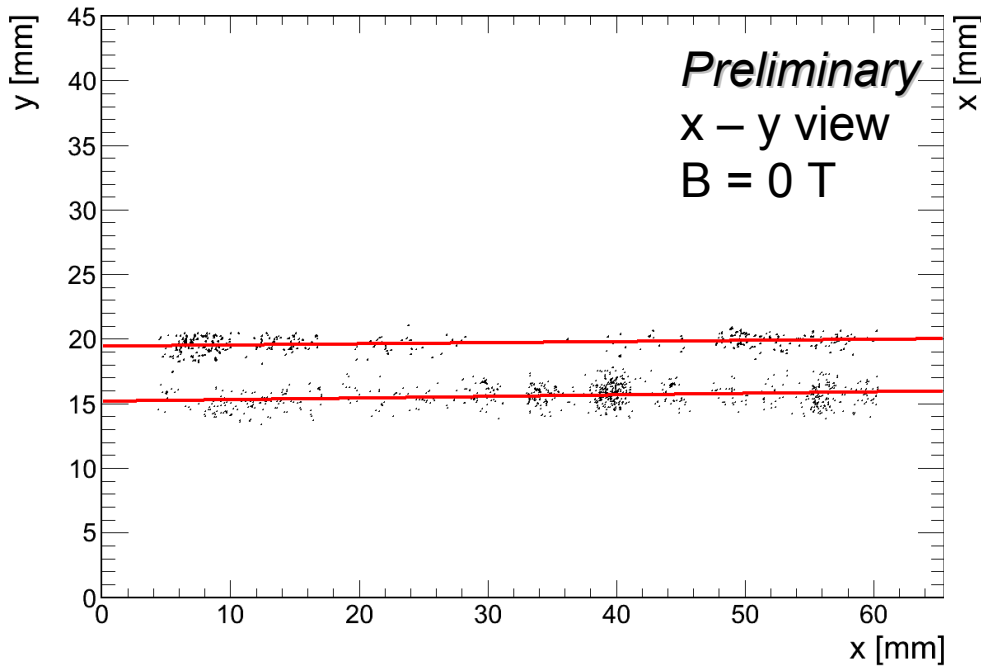
$\Rightarrow$  tracks parallel to x-axis

Cuts:

- Only hits within shutter window
- More than 200 hits per track
- Only single track events
- Tracks centred on lower chip row (z dependent)



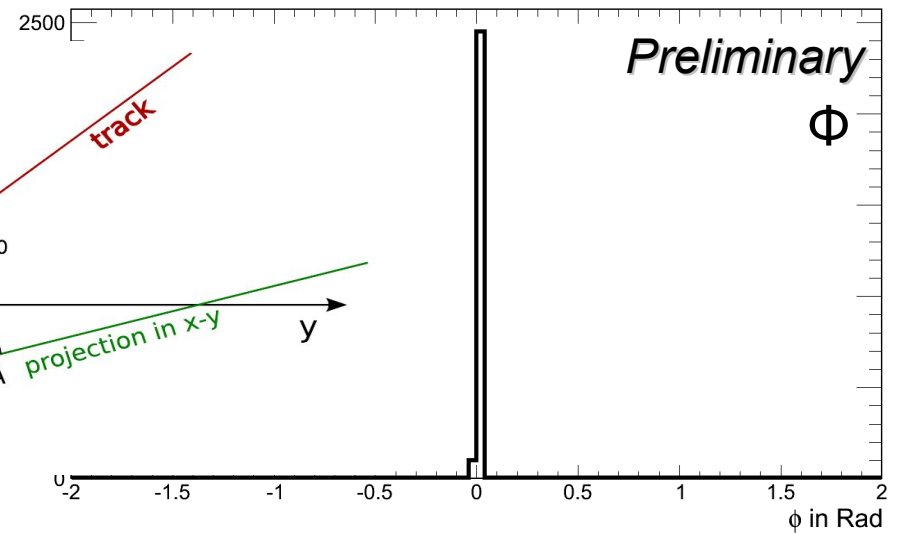
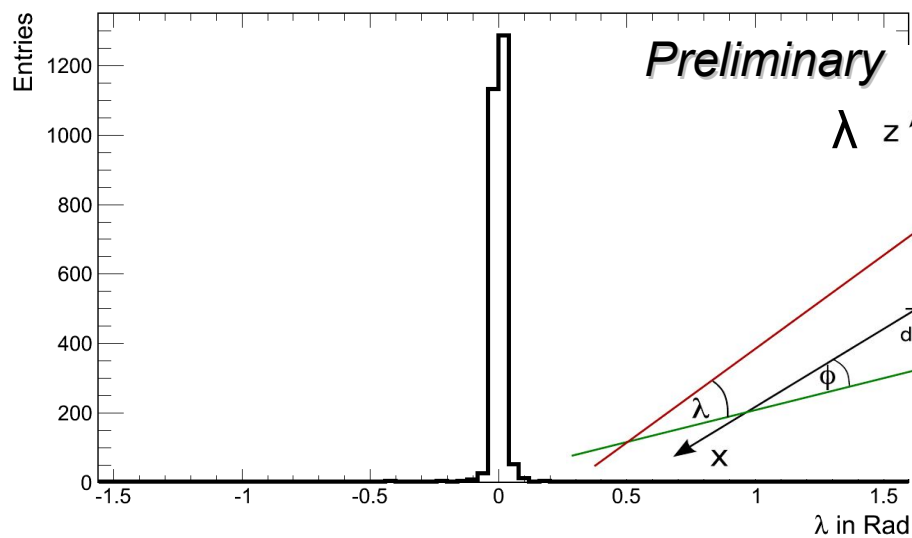
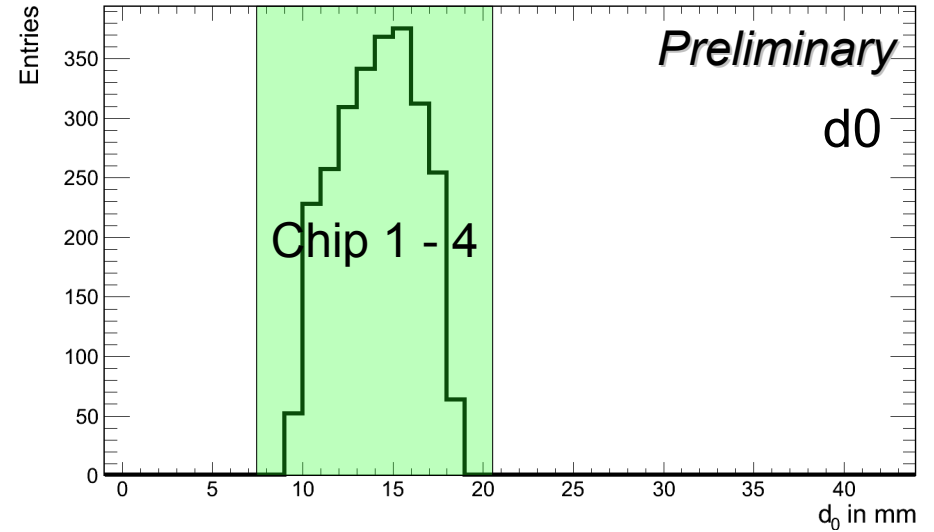
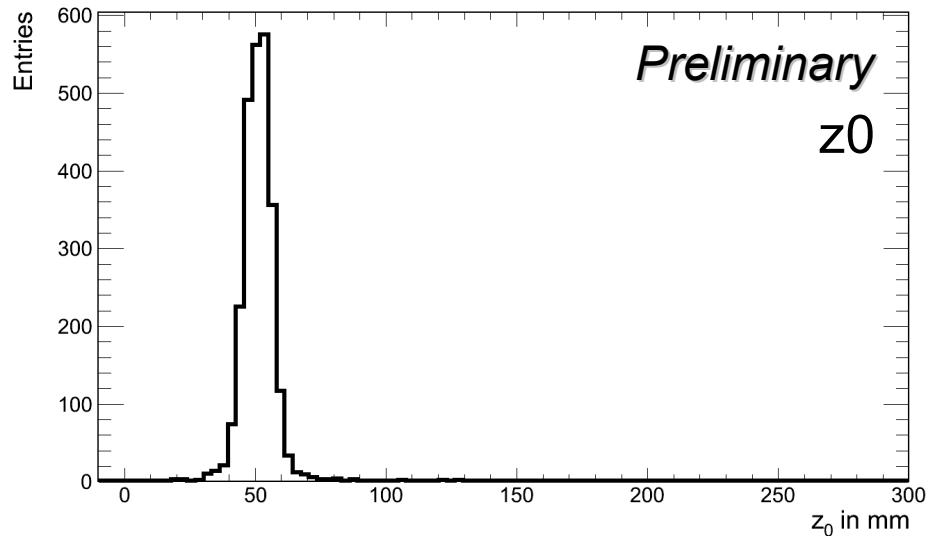
# Reconstructed double tracks



# Track parameters



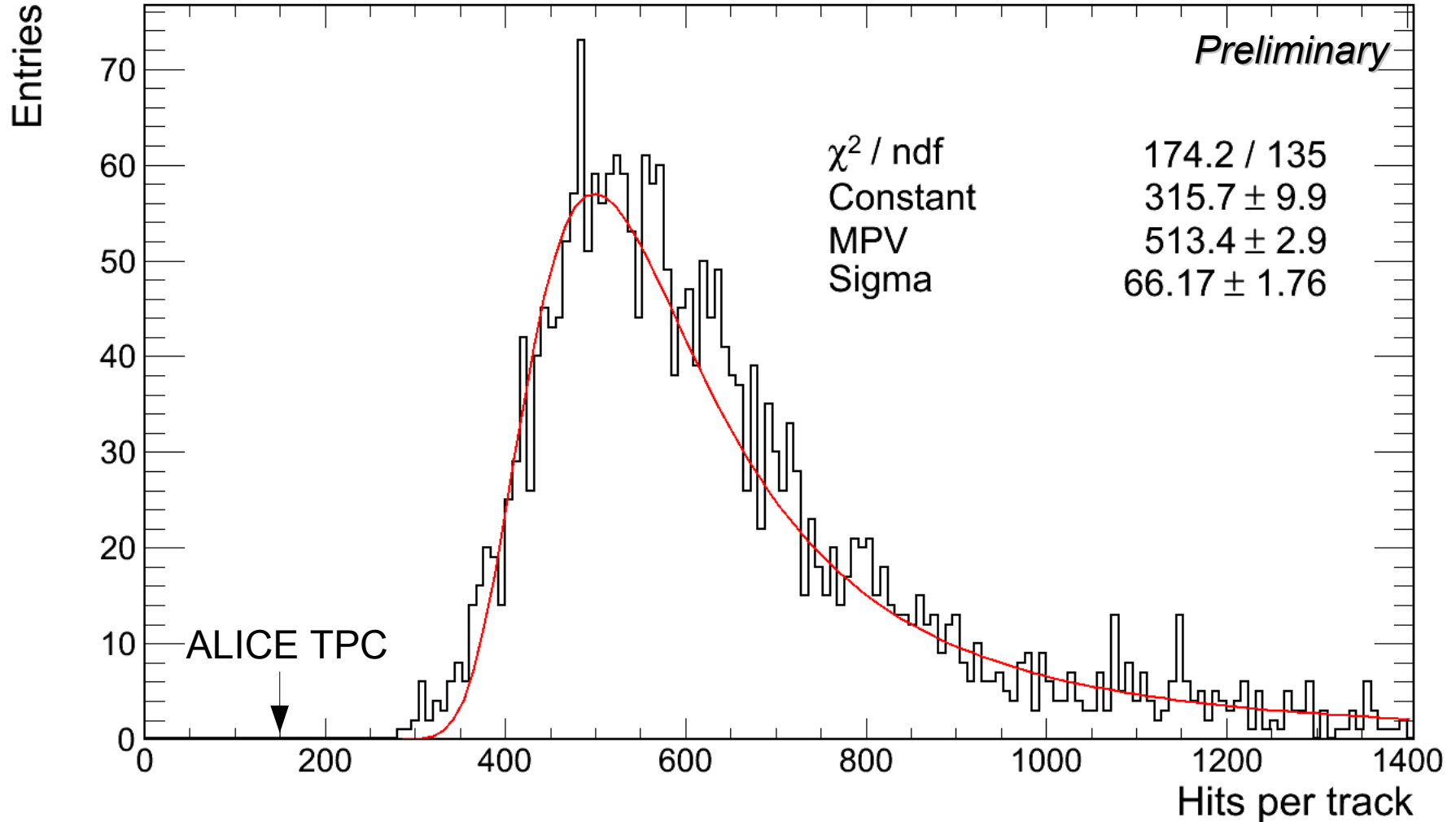
Run:  $z = 5,58$  cm,  $B = 0$  T



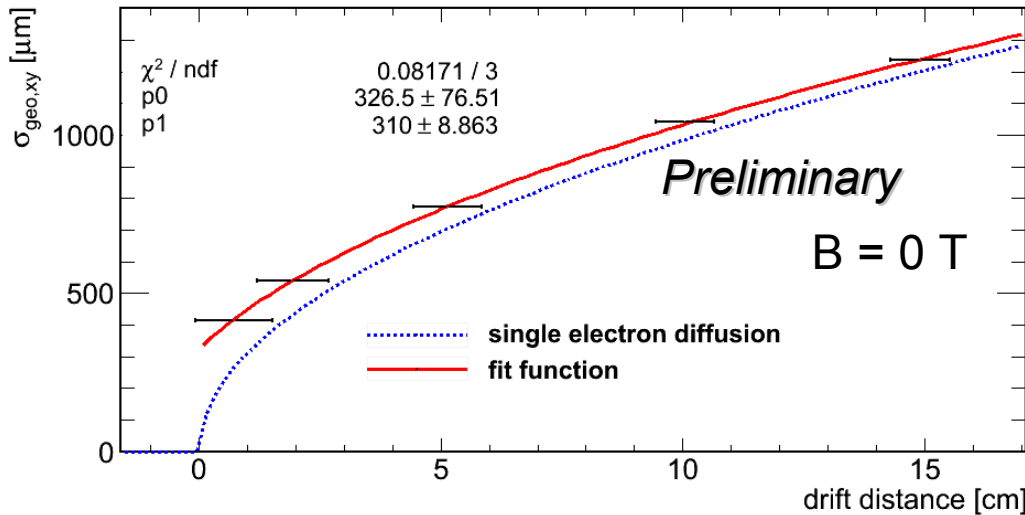
# Hits per tracks



B = 0 T, z = 5,58 cm, track length  $\approx$  5,6 cm

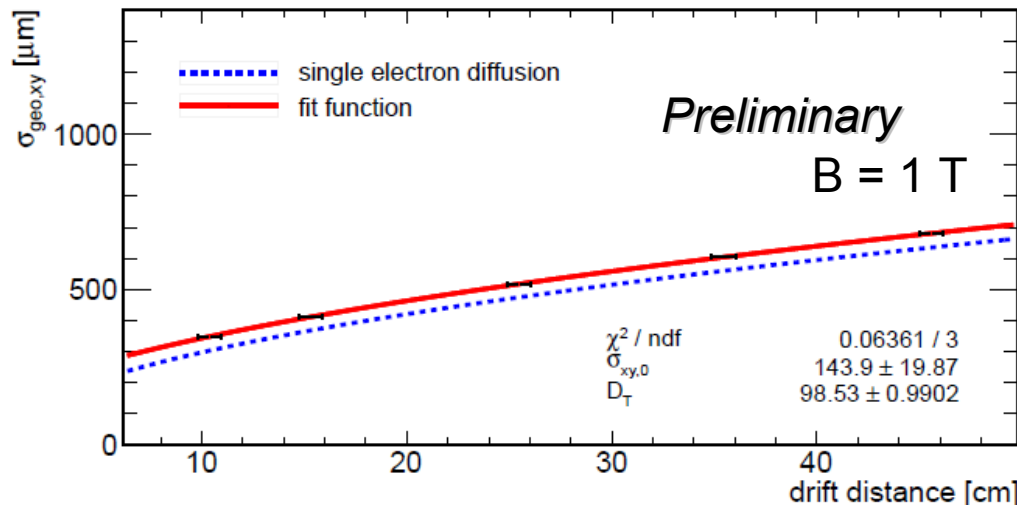


# Transverse spatial resolution

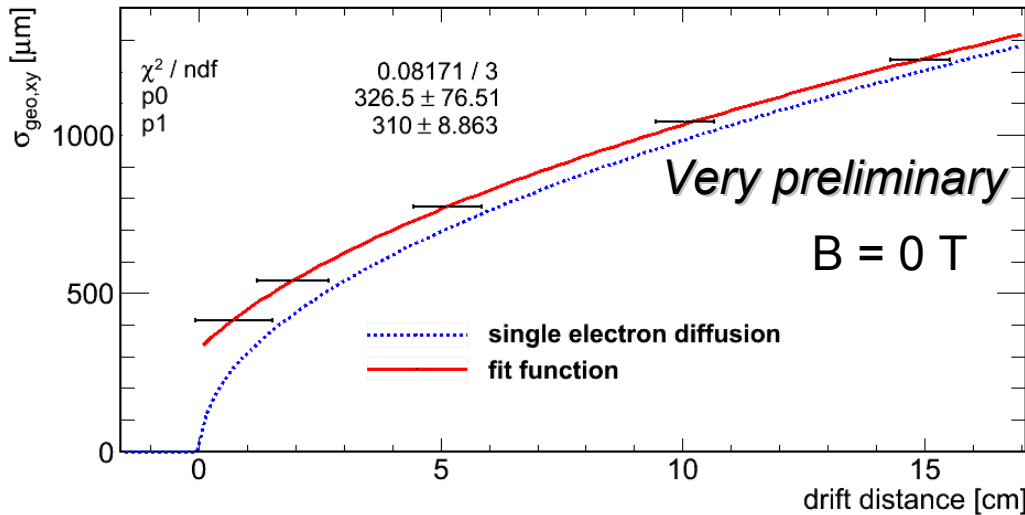


Fit function  $f(x) = \sqrt{P_0^2 + P_1^2 \cdot z}$

P0: intrinsic x-y resolution 327  $\mu\text{m}$   
 dominated by field distortions  
 P1 = 310  $\mu\text{m}/\sqrt{\text{cm}}$ :  
 diffusion in T2K for E = 230 V

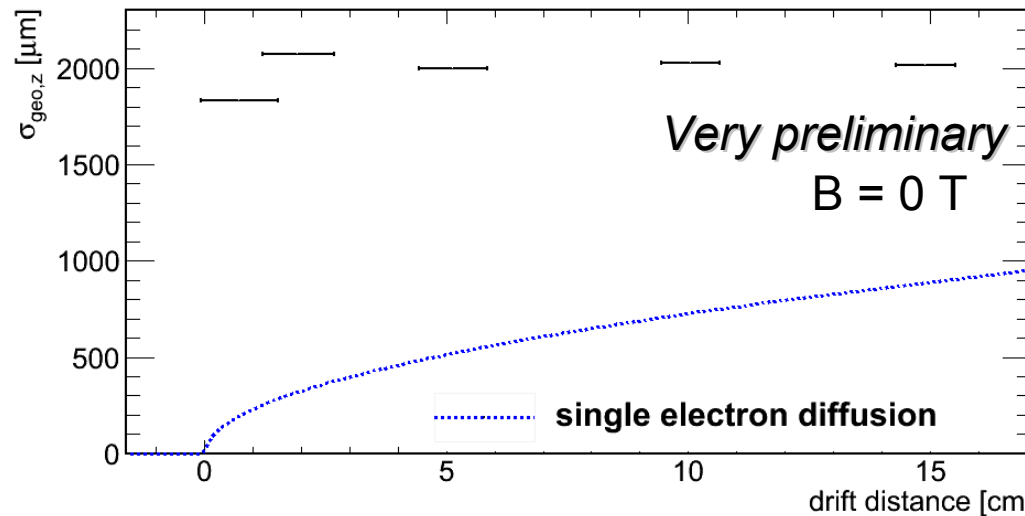


# Preliminary z-scan results



Fit function  $f(x) = \sqrt{P0^2 + P1^2 \cdot x}$

P0: intrinsic x-y resolution 327  $\mu\text{m}$   
 dominated by field distortions  
 P1 = 310  $\mu\text{m}/\sqrt{\text{cm}}$ :  
 diffusion in T2K for E = 230 V



z resolution dominated by

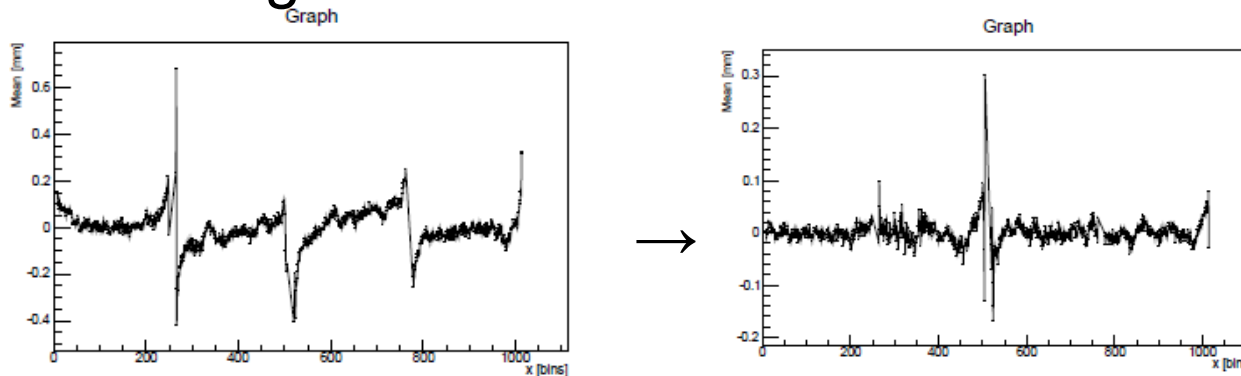
- Clock frequency (25 ns time bins)
- Fast T2K gas ( $v_{\text{Drift}} \approx 73 \text{ mm} / \mu\text{s}$ )
- Timewalk effect

# Data analysis



Martin Rogowski: A new tracking algorithm

- Reinvestigate field distortions of Roberts analysis



- Algorithm from Forward Tracking Detector for ILD



# 2013 testbeam



## Analysis

### Physics:

- Reconstruct tracks, identify characteristics
- Study detector properties
- Study point/track resolution
- Compare to traditional pad readout

